

Title (en)
ELECTRICALLY CONDUCTING CONTACT AND METHOD FOR PRODUCTION THEREOF

Title (de)
ELEKTRISCH LEITFÄHIGER KONTAKT UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)
CONTACT ELECTROCONDUCTEUR ET PROCEDE DE FABRICATION

Publication
EP 1878033 A1 20080116 (DE)

Application
EP 06721946 A 20060504

Priority
• CH 2006000244 W 20060504
• CH 8082005 A 20050506

Abstract (en)
[origin: WO2006119657A1] The invention relates to a contact element (7) for the intermittent contacting of conductor tracks (2, 3) on a circuit board, in particular, for flexible touch pads (4-6), for example for flexible input devices in the automobile industry. According to the invention, a very reliable construction which is particularly suitable for high voltage applications may be achieved, whereby the contact element is made from a metal foam (8). The metal foam is preferably at least partly infiltrated by an elastomeric material which can also be the material of construction of the touchpad. The invention further relates to a method for production of said contact element and touchpads/input devices with such contact pads and the use of said contact pads (7).

IPC 8 full level
H01H 13/785 (2006.01); **H01H 13/79** (2006.01)

CPC (source: EP US)
H01H 13/785 (2013.01 - EP US); **H01H 13/79** (2013.01 - EP US); **H01H 2201/03** (2013.01 - EP US); **H01H 2201/032** (2013.01 - EP US); **H01H 2203/008** (2013.01 - EP US); **H01H 2203/01** (2013.01 - EP US); **H01H 2203/038** (2013.01 - EP US); **H01H 2215/006** (2013.01 - EP US); **H01H 2221/042** (2013.01 - EP US); **H01H 2239/004** (2013.01 - EP US); **Y10T 29/49105** (2015.01 - EP US)

Citation (search report)
See references of WO 2006119657A1

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)
WO 2006119657 A1 20061116; CA 2607408 A1 20061116; CA 2607408 C 20130611; CN 101171654 A 20080430; CN 101171654 B 20101124; EP 1878033 A1 20080116; EP 1878033 B1 20150624; JP 2008541342 A 20081120; JP 5085535 B2 20121128; MX 2007013864 A 20080124; US 2009068857 A1 20090312; US 7964810 B2 20110621

DOCDB simple family (application)
CH 2006000244 W 20060504; CA 2607408 A 20060504; CN 200680015484 A 20060504; EP 06721946 A 20060504; JP 2008509288 A 20060504; MX 2007013864 A 20060504; US 91984106 A 20060504